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AF/2811

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: **Yamaguchi, et al.**

Serial No.: **10/087,556**

Filed: **03/01/2002**

For: **Semiconductor Device and Bump Formation Method**

Docket No.: **TI-31471**

Examiner: **Im, J.M.**

Art Unit:

Conf. No.: **2191**

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LETTER TO THE OFFICIAL DRAFTS PERSON

Commissioner for Patents
Attn: Official Drafts Person
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 on November 14, 2003.


Elizabeth Austin

Dear Sir:

Submitted herewith are 5 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

No fee is believed by Applicant to be due; however, the Commissioner is hereby authorized and requested to charge any necessary fee to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



Michael K. Skrehot
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